



FOR IMMEDIATE RELEASE

CONTACT

SHENMAO America, Inc.
Watson Tseng, General Manager
E-mail: watson_tseng@shenmao.us

SHENMAO wins Global Technology Award for SM-862 Liquid Flux

SAN JOSE, CA — October 2018 — SHENMAO America, Inc. is pleased to announce that it was awarded a 2018 Global Technology Award in the category of Flux for its SM-862 Liquid Flux. The award was presented to the company during a Tuesday, Oct. 16, 2018 ceremony that took place during SMTA International.

SM-862 is a ROL0 (J-STD-004B), tack-free, no-clean flux designed for use in a variety of automated and selective soldering applications. It is a rosin-containing flux designed to leave less residue and minimum bridges. SM-862 produces highly reliable assemblies meeting the toughest reliability requirements. It offers stable quality, good hole-fill, and excellent wettability and solderability.

SHENMAO has successfully been approved by many international well-known electronic manufacturers. The company strives to offer the best quality without compromising cost and time-to-market while providing maximum value to all customers. SHENMAO America, Inc. blends SMT solder paste at its facility in San Jose, CA for distribution in North America.



Premiering in 2005, the Global Technology Awards program is an annual celebration of product excellence in electronics surface mount assembly. Premier products based on the finest examples of creative advancement in technology are chosen by a distinguished panel of industry experts.

For more information, please visit www.shenmao.com.

###

About SHENMAO

SHENMAO is dedicated to the production of solder products including Water Soluble and No-clean Solder Paste, Laser Solder Paste, Solder Preforms, Cored Solder Wire, Wave Solder Bar Alloys, Wave Soldering Fluxes, Extremely Pure Solder Powder up to Type 8, BGA and Micro BGA Solder Sphere, Wafer Level Packaging Solder Paste and Fluxes, LED Die Attach Paste, High Performance Liquid Fluxes, Solder Preform, Solar Ribbon, Plating Anode used in PCB Fabrication, Assembly and Semiconductor Packaging Processes.